



Material Content Data Sheet



Sales Product Name		BSC520N15NS3 G		Issued		29. August 2013		
MA#		MA000527066						
Package		PG-TDSON-8-5		Weight*		124.35 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.835	1.48	1.48	14756	14756
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		304	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		91	
	non noble metal	copper	7440-50-8	37.762	30.37	30.41	303672	304067
wire	non noble metal	copper	7440-50-8	0.066	0.05	0.05	534	534
encapsulation	organic material	carbon black	1333-86-4	0.095	0.08		764	
	plastics	epoxy resin	-	6.749	5.43		54270	
	inorganic material	silicondioxide	60676-86-0	40.681	32.70	38.21	327149	382183
leadfinish	non noble metal	tin	7440-31-5	1.452	1.17	1.17	11674	11674
plating	noble metal	silver	7440-22-4	0.166	0.13	0.13	1331	1331
solder	non noble metal	tin	7440-31-5	0.037	0.03		296	
	noble metal	silver	7440-22-4	0.046	0.04		370	
	non noble metal	lead	7439-92-1	1.758	1.41	1.48	14139	14805
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		180	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		54	
	non noble metal	copper	7440-50-8	22.292	17.93	17.96	179265	179499
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		27	
	non noble metal	iron	7439-89-6	0.011	0.01		91	
	non noble metal	copper	7440-50-8	11.320	9.10	9.11	91033	91151
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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